

ELECTRO-OPTICAL CHARACTERISTICS (25°C Free Air Temperature)								
PARAMETER	TEST COND.	UNITS	MV6152 MV5152	MV6352 MV5352	MV64520 MV5452	MV64521	MV6752 MV5752	
Forward voltage (V_f)	typ.	$I_f=20$ mA	V	2.0	2.1	2.2	2.2	2.0
	max.	$I_f=20$ mA	V	3.0	3.0	3.0	3.0	3.0
Luminous Intensity	min.	$I_f=20$ mA	mcd	17.0	10.0	12.0	30.0	17.0
	typ.	$I_f=20$ mA	mcd	100.0	90.0	25.0	100.0	100.0
Peak wavelength	$I_f=20$ mA	nm	635	585	562	562	635	
Spectral line half width	$I_f=20$ mA	nm	45	35	30	30	45	
Capacitance typ.	$V=0, f=1$ MHz	pF	45	45	20	20	45	
Reverse voltage (V_R) min.	$I_R=100$ μ A	V	5	5	5	5	5	
Reverse current (I_R) max.	$V_R=5.0$ V	μ A	100	100	100	100	100	
Viewing angle (total)	See Fig. 4	degrees	28	28	35	35	28	

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)			
	YELLOW	RED AND H. E. RED	GREEN
Power dissipation	85 mW	120 mW	120 mW
Derate linearly from 25°C (MVX452/4A from 50°C)	1.6 mW/°C	1.6 mW/°C	1.6 mW/°C
Storage and operating temperatures	-55°C to +100°C	-55°C to +100°C	-55°C to +100°C
Lead soldering time at 260° C (See Note 2)	5 sec.	5 sec.	5 sec.
Continuous forward current	20 mA	35 mA	30 mA
Peak forward current (1 μ sec pulse, 0.3% duty cycle)	60 mA	1.0 A	90 mA
Reverse voltage	5.0 V	5.0 V	5.0 V

NOTES
1. The axis of spatial distribution are typically within a 10° cone within reference to the central axis of the device.
2. The leads of the device were immersed in molten solder, at 260°C, to a point 1/16 inch (1.6 mm) from the body of the device per MIL-S-750, with a dwell time of 5 seconds.

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES
(25°C Free Air Temperature Unless Otherwise Specified)

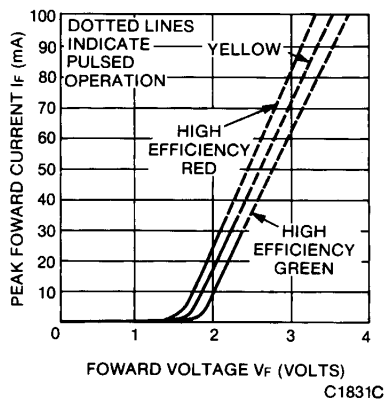


Fig. 1. Forward Current vs. Forward Voltage

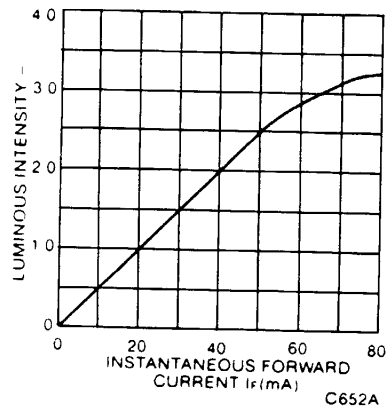


Fig. 2. Luminous Intensity vs. Forward Current

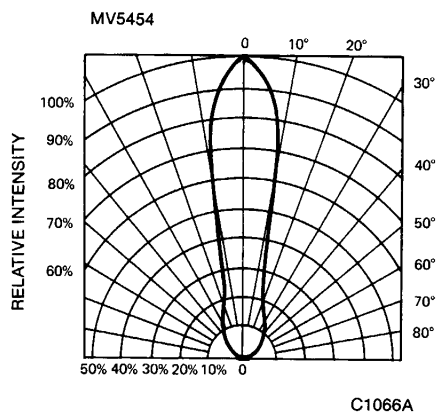


Fig. 3. Spatial Distribution (Note 1)

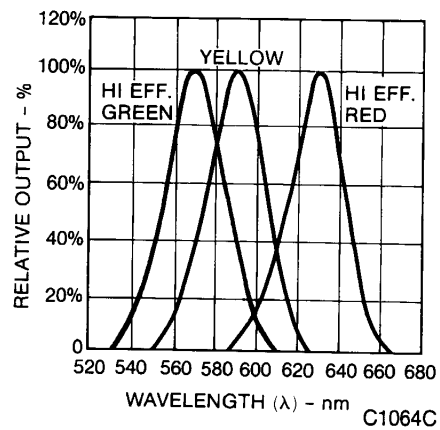


Fig. 4. Spectral Distribution

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